

PCB  
LOGO  
Texas Instruments

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label  
Size: 0.65" x 0.20 "

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

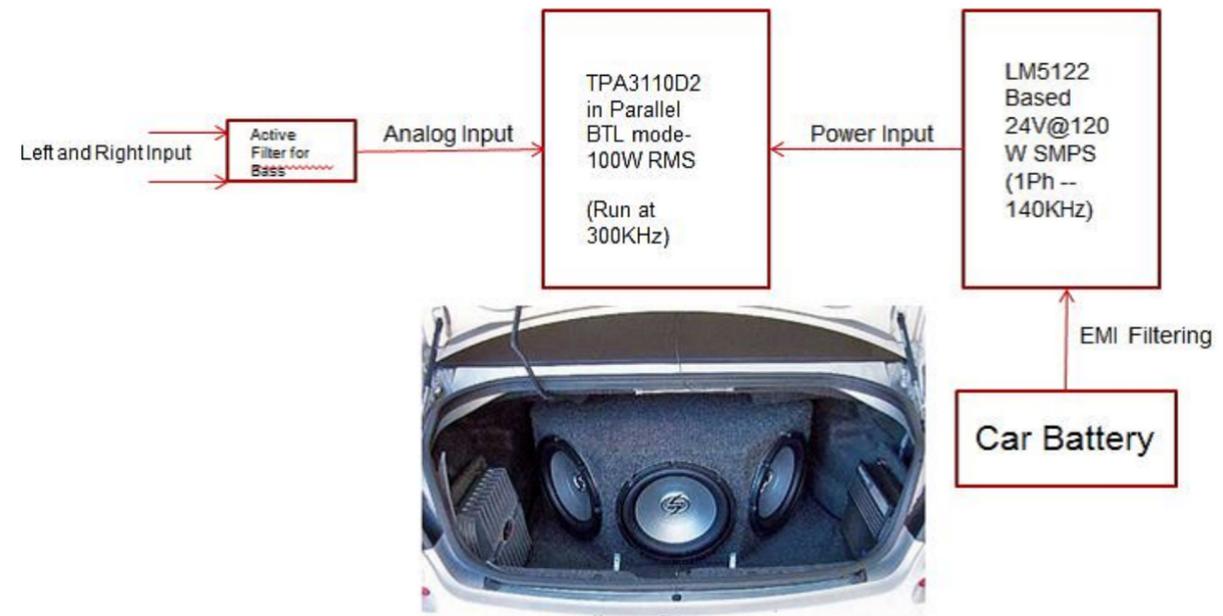
ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 9/26/2014
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet Title:	Sheet: 1 of 4
Drawn By:	File: Hardware_ANSI-B_SchDoc	Size: B	http://www.ti.com
Engineer: Enter name of project lead	Contact: http://www.ti.com/support	© Texas Instruments 2014	



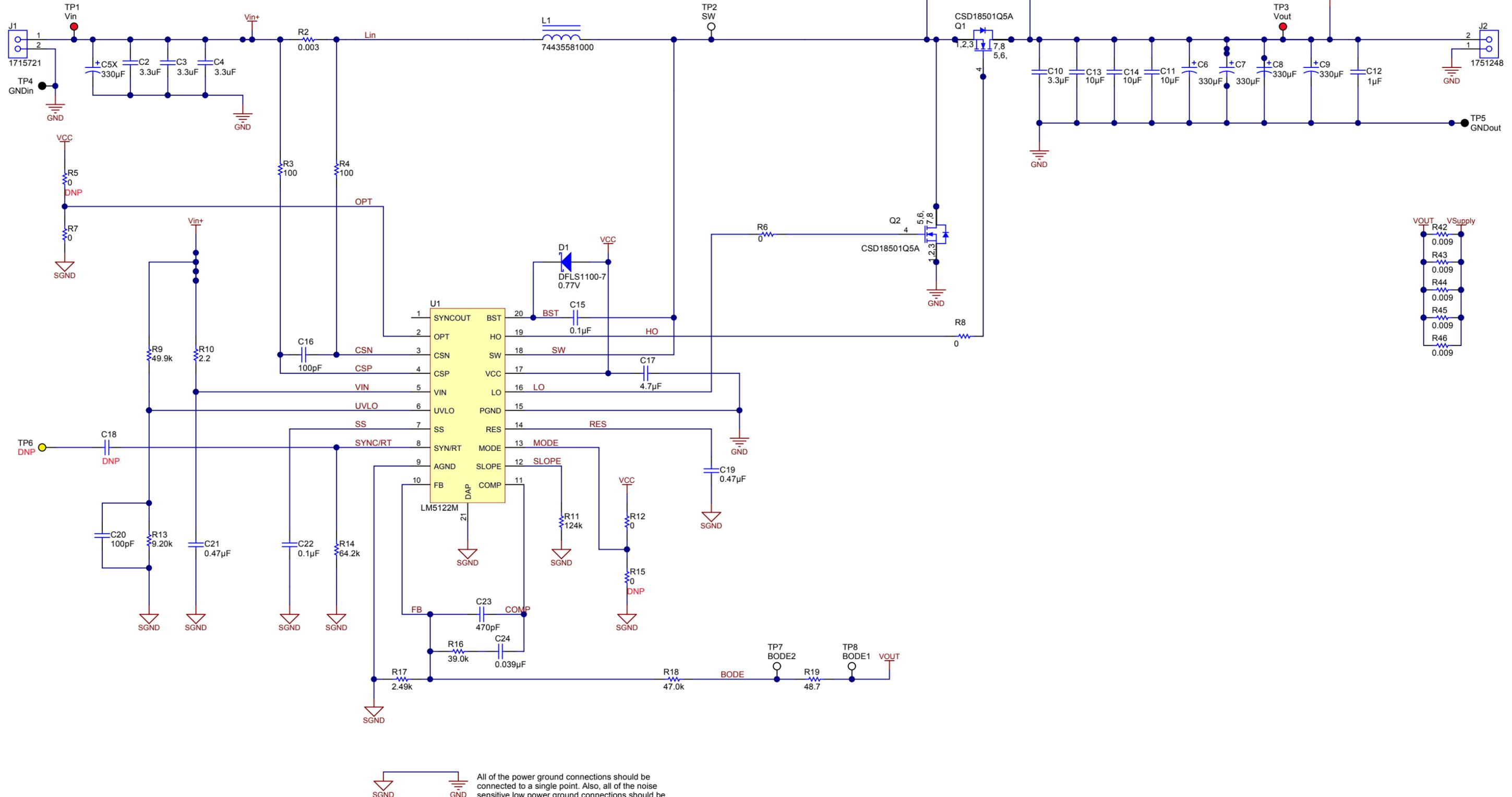
Revision History	
Revision	Notes



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Vin = 8V to 20V DC

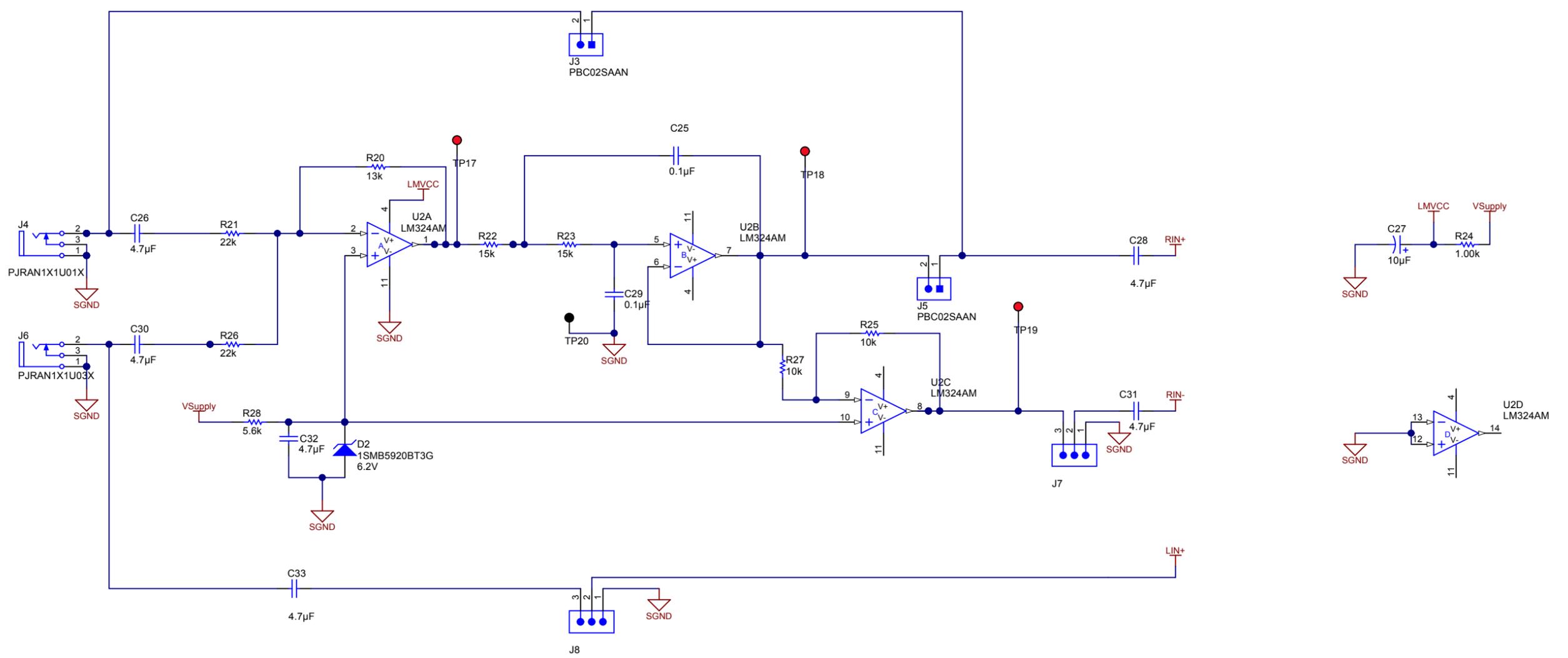
24V @ 5A



All of the power ground connections should be connected to a single point. Also, all of the noise sensitive low power ground connections should be connected together near the AGND pin and a single connection should be made to the single point PGND.

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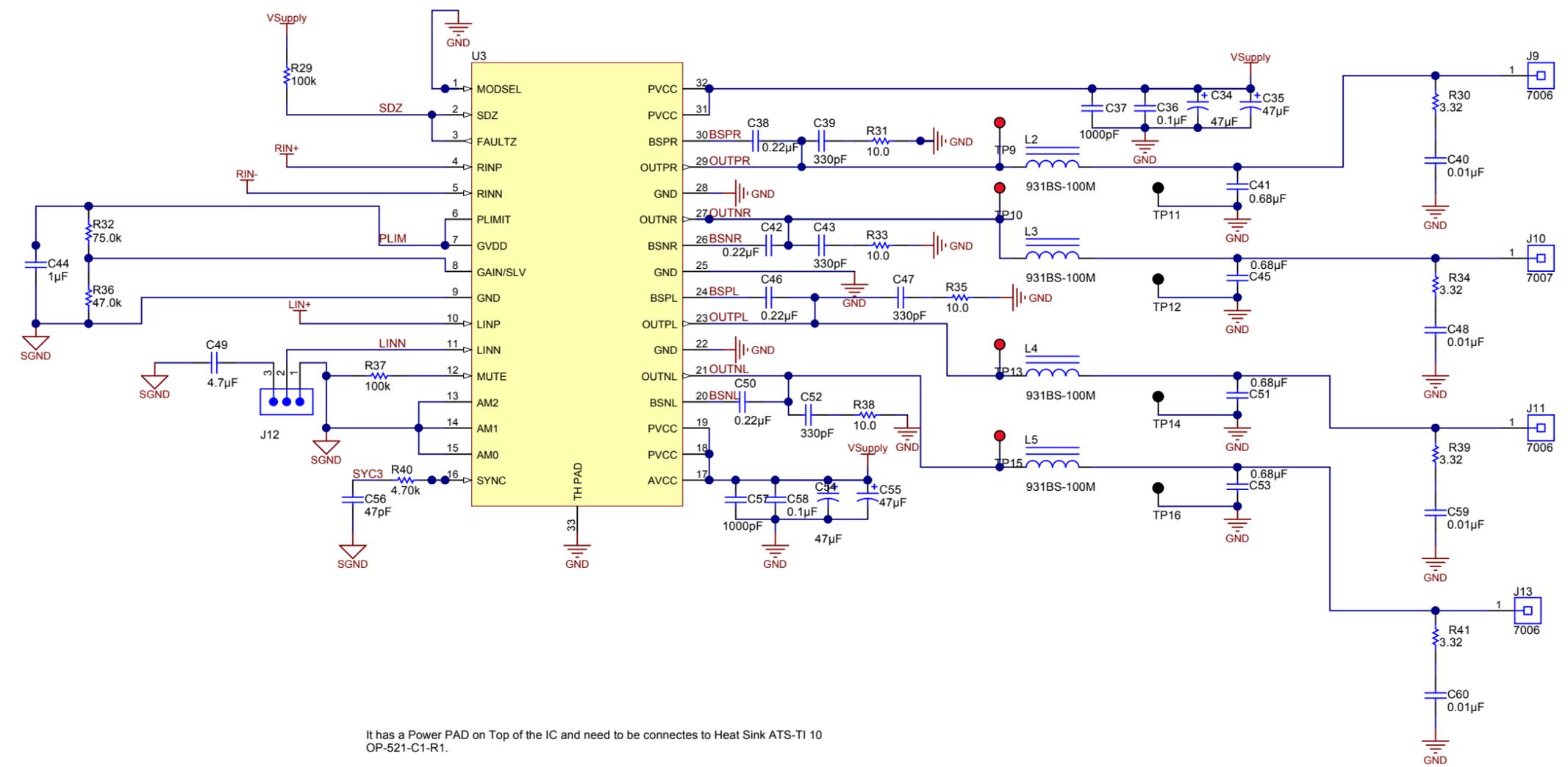
Designed for: Public Release	Mod. Date: 8/20/2014	 TEXAS INSTRUMENTS <a href="http://www.ti.com">http://www.ti.com</a> © Texas Instruments 2014
Project Title: Change in menu Project\Project Options\Parameter	Sheet Title:	
Number: XX####	Rev: E1	
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By:	File: PMP9484 p1.SchDoc	Size: B
Engineer: Enter name of project lead	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



Designed for: Public Release	Mod. Date: 8/19/2014
Project Title: Change in menu Project\Project Options\Parameter	
Number: XX####	Rev: E1
SVN Rev: Not in version control	Sheet Title:
Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:	File: PMP9484 p2.SchDoc
Engineer: Enter name of project lead	Contact: http://www.ti.com/support
	Size: B



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It has a Power PAD on Top of the IC and need to be connects to Heat Sink ATS-T1 10 OP-521-C1-R1.

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